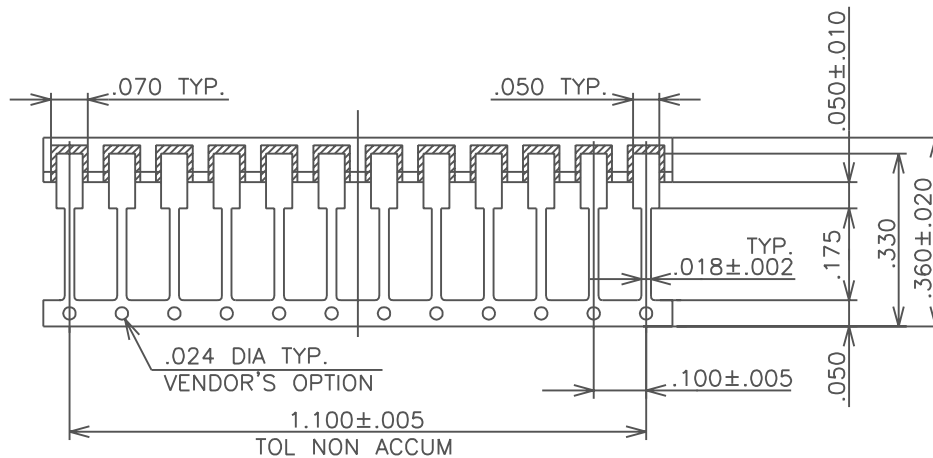


DETAIL-A

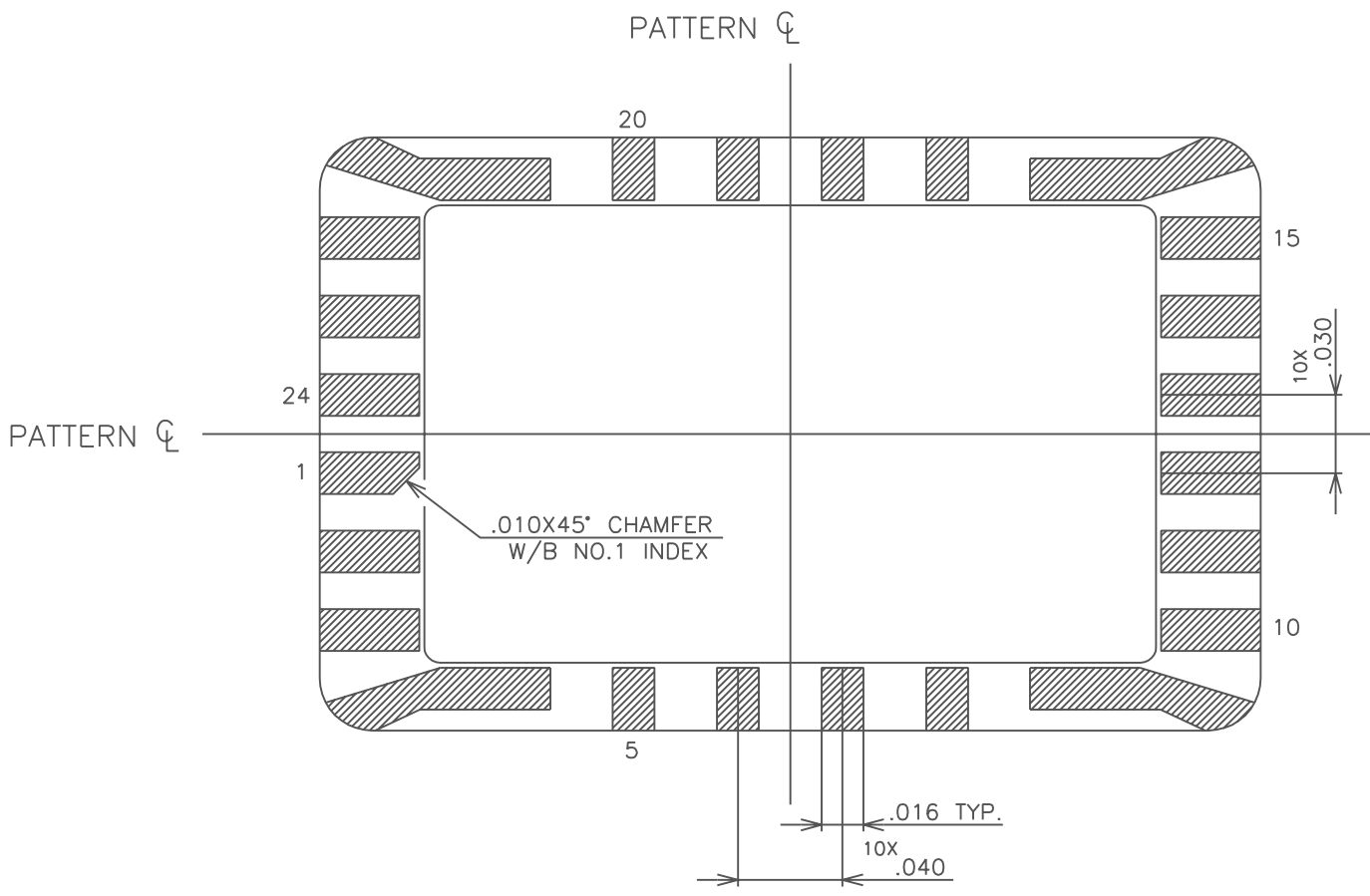
NOTES

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
5. LEAD RESISTANCE : 0.3 OHM MAX.



VENDOR'S OPTION

MODIFICATION						NAME	TOLERANCE	S=0 D=0			
						24 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	DRAWN	CHECKED	APPROVED	DATE
						SCALE 4 / 1	MATERIAL AS INDICATED	T.S/H.K	H.TA/S.NI	H.SA	JAN.13.'01
							±.005 THIRD ANGLE PROJECTION				
	CHANGED	DATE	DRAWN	CHECKED	APPROVED	KYOCERA	KYOCERA CORPORATION KYOTO JAPAN	SSM P/N CSB02477			SHEET 1 / 5



## BONDING PATTERN

MODIFICATION						TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN	CHECKED	APPROVED	DATE
							T.S/H.K	H.TA/S.NI	H.SA	JAN.13.'01
						THIRD ANGLE PROJECTION	/	/		
	CHANGED	DATE	DRAWN	CHECKED	APPROVED		KYOCERA CORPORATION KYOTO JAPAN	SSM P/N CSB02477		SHEET 2/5

NAME 24 LEAD SIDE BRAZED PACKAGE

SCALE 20 / 1

MATERIAL



KYOCERA CORPORATION  
KYOTO JAPAN

SSM P/N  
CSB02477

SHEET  
2/5